*Please make sure that you read carefully the Legal Statement and About the Company' s Snapshot before reading the PDF and be aware that the information contained in the webpage shall always prevail over the PDF under any circumstances.

Tianshui Huatian Technology Co., Ltd.

Code: 002185 ISIN: CNE100000825

Founded	12/25/2003	Email	htcwy2000@163.com
Listing	11/20/2007	Telephone	(+86)0938-8631816、0938-8631990
Website	www.ht-tech.com	Fax	(+86)938-8214627
Domicile	No.14, Shuangqiao Road, Qinzhou District, Tianshui, Gansu	Office	No. 88, Chiyu Road, Qinzhou District, Tianshui, Gansu

Business Summary (Updated: 08/30/2023)

The IC industry, which the company belongs to, with its complicated technology and highly specialized industrial structural dependency, segmented into three phases,IC Design, Chip Manufacturing, IC Assembly and Test according to the processing flow. IC industry design oriented, it determined the chip function and application field. Once the Design Houses completed its design scheme, they entrusts to the Foundry to do the chips manufacturing in a wafer form, and then place orders to 3rd-party OSAT(Outsourced Semiconductor Assembly and Test) company like us to finish the assembly and test, then sell the product to downstream enterprise who are making the final electronic devices. There is another type of business model in IC industry like Samsung and Intel who complete the whole process by their own facility so called IDM (Integrated Devices Manufacturer).

The company is the Top 10 IC Assembly and Test Company world-wide. Its main business model is to provide professional IC assembly and test services according industry technical standards and specifications to fulfill customers special requirements. The company has always adhered to our Quality Policy of "Our job is to make the customer satisfied" and Business Philosophy of "Customer First, Quality First". After long-term unremitting efforts, the company has established solid relationship with more than 800 domestic and oversea customers. Currently, the company has established manufacturing facilities in Tianshui, Xi'an, Kunshan, Shanghai, Nanjing, Chengdu in mainland China and Ipoh, Malaysia. The pofortlio of IC Assembly includes DIP/SDIP, SOT, SOP, SSOP, TSSOP/ETSSOP, QFP/LQFP/QFN/DFN, BGA/LGA, FlipChip, MCM (MCP), SiP, WLP, TSV, Bumping, MEMS and etc. Major application fields are Computer, Network Communications, Consumer electronics and smart mobile terminals, Internet of Things, Industrial, Automotive, HPC and etc.

As a high-tech enterprise, the Company has accumulated a large number of IC assembly and test technologies with independent intellectual property rights and has taken a leading position in the domestic industry in technical strength, production scale and economic benefits, through continuous technological innovation. The company undertook the R & D tasks of a number of major science and technology projects (topics) of "VLSI (Very Large Scale Integrated Circuit) Manufacturing Technology and integrated Process " and awarded the honorary title of "Trusted Brand in Chinese Semiconductor Market", "Most Influential Enterprise in Chinese Semiconductor Market" And "China's Top Ten Semiconductor Assembly and Test Companies," and other honorary title , and vary products and technologies were named "China's Semiconductor Innovation Products and Technologies.

Highlights (Updated: 08/30/2023)

Technical competence: The Company enhanced R & D investment by perfecting the R & D simulation platform and participating National Science and Technology 02 Major Project and other technological innovations and continuously research and development of new products, new technology, and new process. The company has developed FlipChip, Bumping, MEMS, MCM (MCP), WLP, SiP, TSV, Fan-Out and other advanced packaging technology and products independently.

Sales Network: The Company has a solid customer base and a wide-spreaded sales network, has made presence globally, thus providing a strong market guarantee for the company's further growing.

Scalable efficiency: The Company keeps high CapEx on the capacity and technical capability ramp-up. At the same time, it has maintained a sustainable and healthy development through continuous technical and management innovation.

Management team: The Company has a strong management team with experienced operating skills, innovative vision, high unity and upward spirit. The company has formed a set of advanced large-scale production management system through years of production practices.

Investment Risks (Updated: 08/30/2023)

1、 The risk affected by the economic conditions in the semiconductor industry

The company' s performance is closely related to the prosperity of the semiconductor industry. The fluctuations of the semiconductor industry may bring uncertain risks to the company. In addition, with the increasingly fierce competition in the IC assembly and test industry, it will also increase the difficulties of operating the company.

2、The risk of rising product costs

Risk of Rising Production Costs Price fluctuations of essential raw materials and the escalation of labor costs may pose challenges to the company's cost control efforts.

3、The risk of R & D and new product development failures

The rapid development of IC market and frequent iteration of electronic products make it necessary for companies to continuously accelerate the pace of R & D and new product development. If the R & D capability and the development of new products cannot meet the needs of the market and customers, the company will face the risk of technology R & D and new product development failure.

4、The risk of impairment of goodwill

In January 2019, the company completed the acquisition of Unisem, a listed company on the Main Market of Malaysia. The acquisition of Unisem constitutes a business combination of entities under different controls. According to the "Enterprise Accounting Standards," the difference between the company's acquisition cost and the fair value of identifiable net assets is recognized as goodwill.

If in the future, factors such as macroeconomic downturn, cyclical fluctuations in these semiconductor industry, intensified industry competition, or significant adverse changes in Unisem's technological research and

Trading Information

CSRC Sector	Manufacturing
CSRC Subsector	Computers, Communication Equipment, and Other Electronic Equipment Manufacturing
Market	Main Board of Shenzhen Stock Exchange

Directors & Executives

Chairman of the Board:	Xiao Shengli
General Manager:	Zhang Tiecheng
Chief Financial Officer:	Song Yong
Board Secretary:	Chang Wenying
Board Members:	Xiao Shengli,Zhang Tiecheng,Xiao Zhiyi,Cui Weibing,Zhang Haodai,Liu Jianjun,Xu Huanzhang,He Xiaoning,Yu Xiekang

Top 5 Shareholders (Ended: 06/30/2026)

Name	Shares Held(M.)	%Own
Tianshui Huatian Electronics Group Co., Ltd.	727.84	21.88
Hong Kong Securities Clearing Company Limited	82.83	2.49
Huaxin Investment Management Co., Ltd. - National Integrated Circuit Industry Investment Fund Phase II Co., Ltd.	72.55	2.18
Guangdong Hengkuo Investment Co., Ltd.	17.15	0.52
Zhang Yuejun	12.00	0.36

Operating Revenue (Unit: Million)

	1Q	Semi-annual	3Q	Annual
2026	4,800	10,511	-	-
2025	3,569	7,780	12,380	17,214
2024	3,106	6,718	10,531	14,462
2023	2,239	5,089	8,068	11,298
2022	3,008	6,221	9,127	11,906
2021	2,597	5,618	8,867	12,097
2020	1,692	3,715	5,917	8,382
2019	1,711	3,839	6,107	8,103
2018	1,928	3,786	5,559	7,122
2017	1,486	3,312	5,324	7,010

development, market expansion, and operational management were to occur, leading to an operational performance that falls short of expectations, it may be necessary to recognize impairment of the goodwill. This could have an adverse impact on the company's operational performance.

Dividend Data

Cash Div./Share( )	Bonus Issue/Share	Stock Div./Share	Date Decl.	Ex-Div.Date	Record Date	Cash Pay Day	Share Pay Day
0.022	-	-	06/03/2026	06/10/2026	06/09/2026	06/10/2026	-
0.058	-	-	04/24/2025	05/06/2025	04/30/2025	05/06/2025	-
0.022	-	-	06/12/2024	06/20/2024	06/19/2024	06/20/2024	-
0.026	-	-	06/14/2023	06/21/2023	06/20/2023	06/21/2023	-
0.045	-	-	06/22/2022	06/29/2022	06/28/2022	06/29/2022	-
0.022	-	-	06/10/2021	06/18/2021	06/17/2021	06/18/2021	-
0.015	-	-	06/16/2020	06/24/2020	06/23/2020	06/24/2020	-
0.020	-	-	05/24/2019	05/31/2019	05/30/2019	05/31/2019	-
0.020	-	-	06/12/2018	06/20/2018	06/19/2018	06/20/2018	-
0.050	1.000	-	06/14/2017	06/20/2017	06/19/2017	06/20/2017	06/20/2017

Per Share Data (FYE: 12/31)

	2025	2024	2023	2022	2021	2020	2019	2018	2017	2016
Earnings( )	0.2200	0.1923	0.0706	0.2353	0.5025	0.2561	0.1134	0.1829	0.2324	0.3669
Prices: High( )	13.51	14.52	11.03	12.90	16.30	20.80	7.63	8.86	14.63	17.98
Prices: Low( )	8.48	5.65	8.00	7.75	11.12	7.36	3.81	3.66	6.59	11.42

Financials

Income Statement (Unit: Million ; FYE: 12/31)

	2025	2024	2023	2022	2021	2020	2019	2018	2017	2016
Operating Revenue	17,214	14,462	11,298	11,906	12,097	8,382	8,103	7,122	7,010	5,475
Operating Costs	14,932	12,716	10,292	9,901	9,120	6,565	6,780	5,959	5,755	4,487
Operating Income	882	689	233	1,077	1,905	909	356	489	629	416
Pretax Income	885	692	231	1,069	1,894	908	359	480	631	478
Income Tax	78	33	-47	47	175	88	66	51	84	65
Net Income	806	659	278	1,023	1,718	820	293	429	547	413

Balance Sheet (Unit: Million ; FYE: 12/31)

	2025	2024	2023	2022	2021	2020	2019	2018	2017	2016
Assets										
Monetary Capital	5,368	5,153	5,469	5,249	7,133	2,907	2,128	3,097	932	1,195
Current Assets-Total	13,935	12,043	11,143	9,901	11,452	6,094	4,822	5,579	3,583	3,169
Non-current Assets-Total	29,186	26,193	22,609	21,070	18,522	13,215	11,223	6,864	5,783	4,508
Total Assets	43,121	38,236	33,752	30,971	29,974	19,309	16,045	12,443	9,366	7,677
Liabilities										
Current Liabilities-Total	14,459	9,863	9,612	8,151	8,175	5,013	4,059	4,420	2,706	1,829
Long-term Debt	5,863	7,062	4,032	2,656	3,010	2,052	1,506	1,374	409	76
Non-current Liabilities-Total	7,178	8,058	5,016	3,622	3,835	2,670	2,067	1,648	665	343
Total Liabilities	21,637	17,922	14,628	11,773	12,010	7,683	6,126	6,068	3,371	2,172
Stockholder's Equity										
Share Capital	3,264	3,204	3,204	3,204	3,204	2,740	2,740	2,131	2,131	1,066
Retained Profits	6,193	5,691	5,194	5,064	4,478	3,178	2,557	2,203	1,891	1,482
Total Owners' Equity	21,484	20,314	19,124	19,198	17,964	11,626	9,919	6,375	5,996	5,505

Cash Flow Statment (Unit: Million ; FYE: 12/31)

	2025	2024	2023	2022	2021	2020	2019	2018	2017	2016
Net Cash Flows-Operating	3,472	3,098	2,411	2,877	3,444	2,058	1,765	1,133	904	863
Net Cash Flows-Investing	-4,922	-5,245	-4,369	-5,329	-5,679	-3,058	-3,983	-1,450	-1,694	-1,440
Net Cash Flows-Financing	1,683	1,713	2,105	692	6,471	1,813	1,092	2,688	562	-420